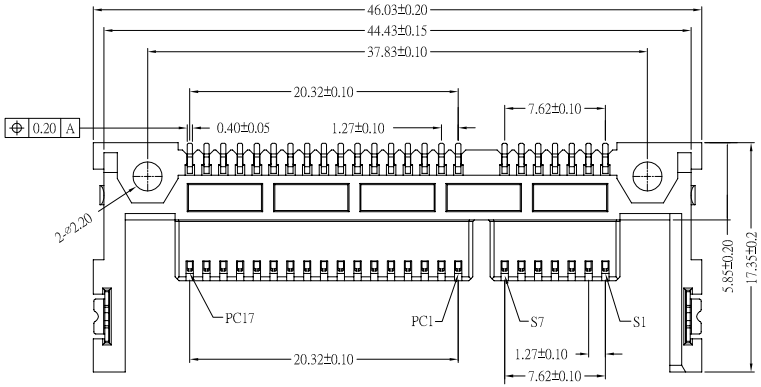
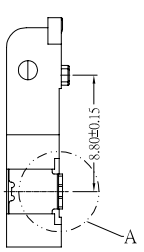
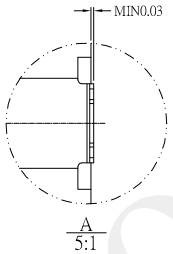








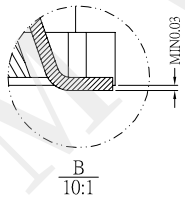
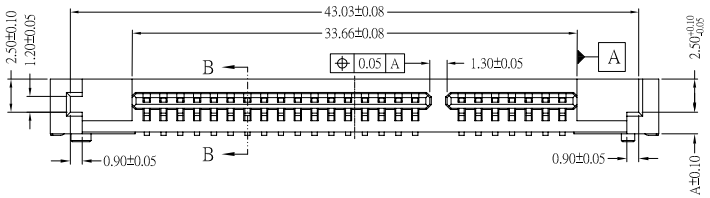
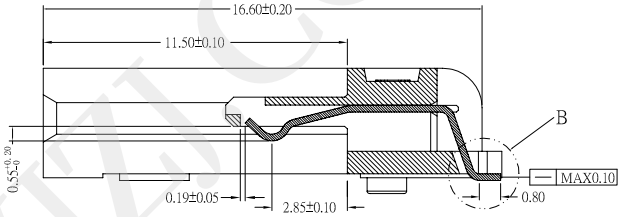


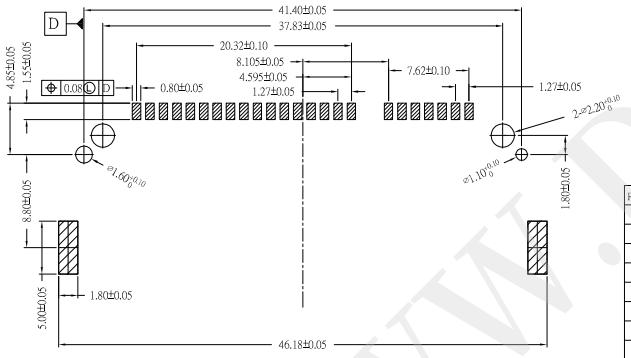
Table one

TYPE	PIN數	DIM"A"
A	17+7	1.65
B	17+7	1.30





SECTION B-B SCALE 2/1



PIN NO.	NAME	TYPE	DESCRIPTION	PIN NO.	NAME	TYPE	DESCRIPTION
S1	SGND	Signal GND	Ground for signal integrity	PC6	TBD	TBD	
S2	A+	SATA Differential	Signal pair A	PC7	GND	Device GND	
S3	A-	SATA Differential		PC8	LED1	LED Output	LED Output
S4	SGND	Signal GND	Ground for signal integrity	PC9	LED2	LED Output	LED Output
S5	B-	SATA Differential	Signal pair B	PC10	IO1	CMOS Input/output	Reserved Input/output
S6	B+	SATA Differential		PC11	IO2	CMOS Input/output	Reserved Input/output
S7	SGND	Signal GND	Ground for signal integrity	PC12	IO3	CMOS Input/output	Reserved Input/output
PC1	CDI	CMOS Input		PC13	PWR	3.3V	Device Power(3.3V)
PC2	GND	Device GND		PC14	PWR	3.3V	Device Power(3.3V)
PC3	TBD	TBD		PC15	PGND	Device GND	Device Ground
PC4	TBD	TBD		PC16	PGND	Device GND	Device Ground
PC5	TBD	TBD		PC17	COD	CMOS Output	Card Detect Out

NOTES:
(1).ELECTRICAL：
CURRENT：1.5A
CONTACT RESISTANCE：30MΩ MAX
DIELECTRIC WITHSTANDING：500V AC
INSULATION RESISTANCE：1000MΩ MIN
(2).MECHANICAL：
CONTACT RETENTION TO HOUSING：3.7N MIN
MATING FORCE：24.5N MAX
UNMATING FORCE：3.7N MIN
DURABITITY：10,000 CYCLES
(3).MATERIAL：
INSULATOR：LCP
COLOR：BLACK
CONTACT：PHOSPHOR BRONZE
(4).PLATING：
CONTACT AREA： GOLD PLATED
UNDER PLATING：NICKEL OVERALL
SOLDER TAIL AREA：TIN

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TOLERANCE: X.X ±0.30, X.XX ±0.25, X.XXX ±0.15, X.° ±2°, X.X° ±0.5°	DRAWED BY：陈一鸣	DATE：2014-02-23	PART NAME: C-FAST 7+17P 公座
UNIT: mm [inch]	CHECKED BY：马跃	DATE：2014-02-23	PART NO. HYC41-CF24-414-X
SCALE:1:1 SIZE: A4	APPROVED BY：邱敏	DATE：2014-02-23	MOLD NO. / DRAW NO: HYC-2604241055 / SHEET NO. 1 OF 1

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